

16ECT72 - RF AND MICROWAVE ENGINEERING

Unit III – Microwave Solid State Devices

IMPATT Diode (Operation, Physical description and Applications)

Course Handling Faculty

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Course Outcome 3

CO3	Analyze the characteristics of microwave solid state devices with its application
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Learning Outcome 1

LO1	Examine the construction and operation of microwave semiconductor devices
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Avalanche Transit Time Devices

- IMPATT Diode
- TRAPATT Diode
- BARITT Diode

Introduction

- Rely on the effect of voltage breakdown across a reverse biased p-n junction.
- The avalanche diode oscillator uses carrier impact ionization and drift in the high field region of a semiconductor junction to produce a negative resistance at microwave frequencies.

Negative Resistance Effect

1. The impact ionization avalanche effect, which causes the carrier current $I_0(t)$ and the ac voltage to be out of phase by 90°
2. The transit-time effect, which further delays the external current $I_e(t)$ relative to the ac voltage by 90°

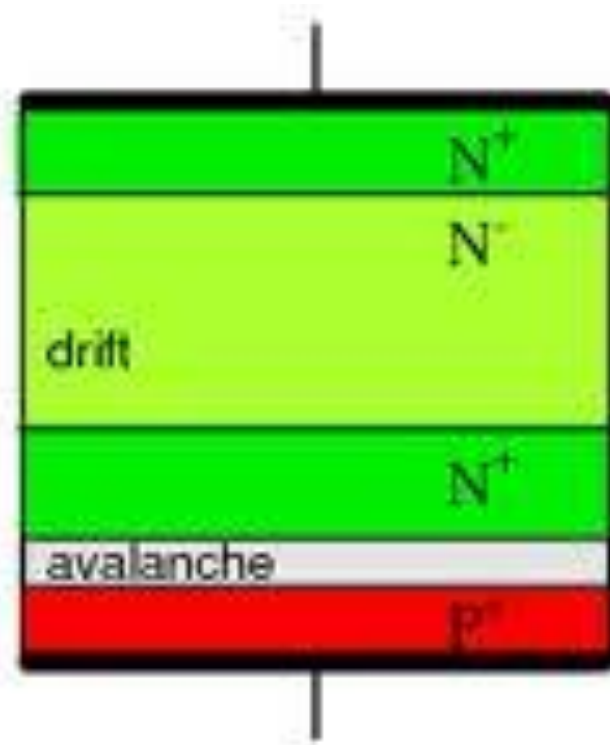
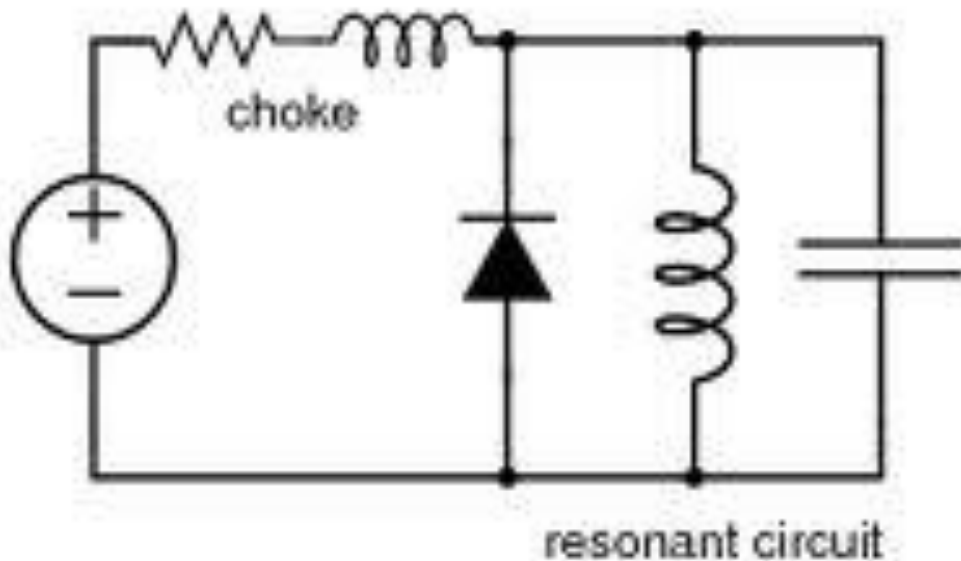
Two distinct modes of avalanche oscillator is observed

- 1) IMPATT (IMPact ionization Avalanche Transit Time operation)
 - DC-to-RF c.e. is 5 to 10%
 - 2) TRAPPAT (Trapped Plasma Avalanche Triggered Transit operation)
 - 20 to 60%
- Another type of active microwave device is BARITT (Barrier Injected Transit Time Diode)

Introduction

- Form of high power diode used in high frequency electronics and microwave devices
- Typically made from silicon carbides due to their high breakdown fields.
- Frequency - 3 to 100 GHz
- High power capability
- From low power radar systems to alarms
- Generate high level of phase noise – avalanche process

IMPATT Diode as oscillator



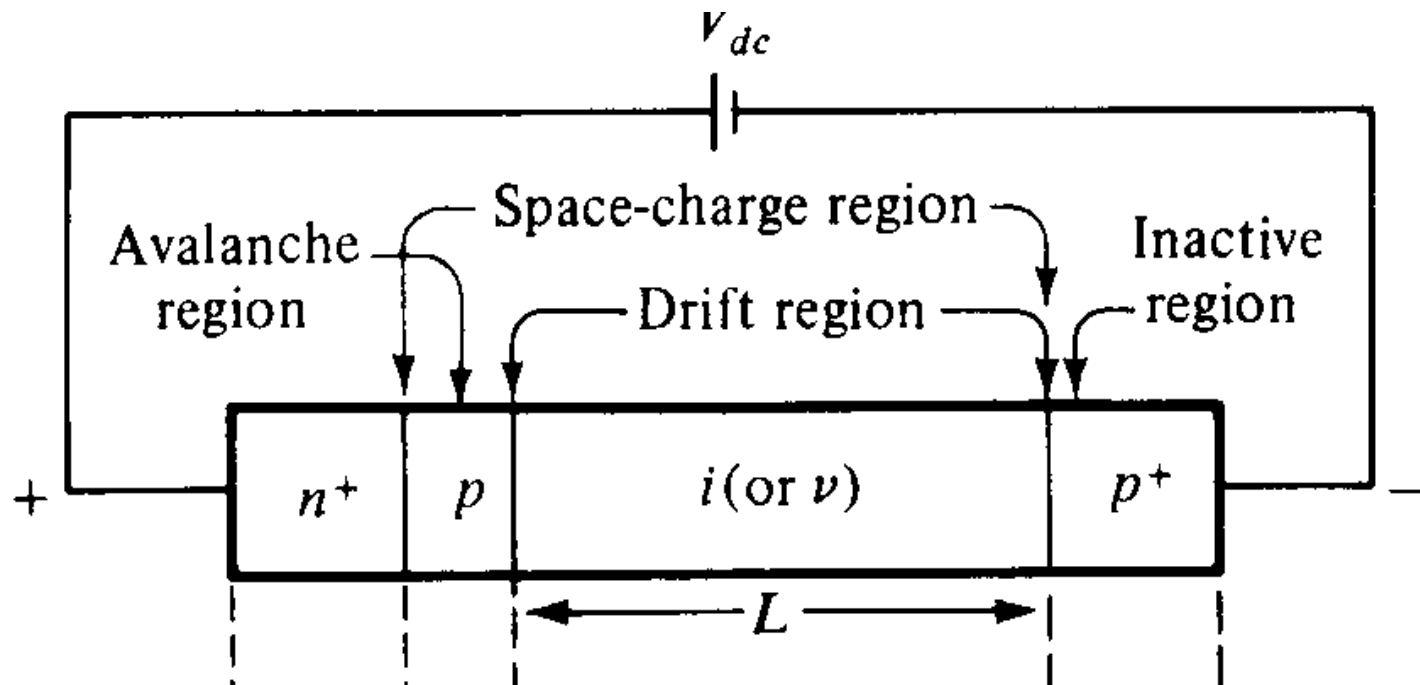
IMPATT Diode

- The IMPATT diode family includes many different junctions and metal semiconductor devices.
- The first IMPATT oscillation was obtained from a simple silicon p-n junction diode biased into a reverse avalanche break down and mounted in a microwave cavity.

Avalanche Effect and Transit Time Effect

- Electron–hole pairs are generated in the high field region. The generated electron immediately moves into the N region, while the generated holes drift across the P region.
- The time required for the hole to reach the contact constitutes the transit time delay.

Physical Description – Read Diode



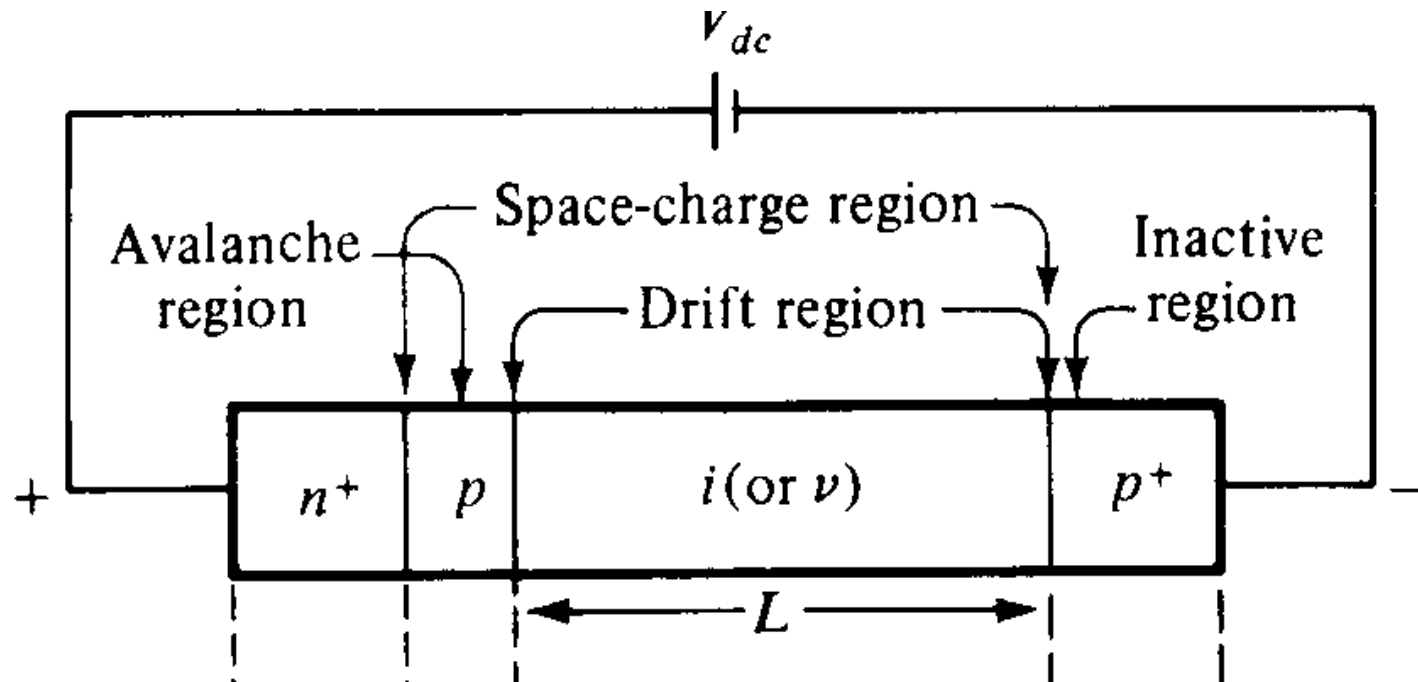
Physical Description – Read Diode

- The original proposal for a microwave device of the IMPATT type was made by **Read**. Read diode is the basic type in the IMPATT diode family

The Read diode consists of two regions:

- 1) The Avalanche region (a region with relatively high doping and high field) in which avalanche multiplication occurs and
- 2) the drift region (a region with essentially intrinsic doping and constant field) in which the generated holes drift towards the contact.

Physical Description – Read Diode



Physical Description

$$n^+ - p - i - p^+$$

- + very high doping
- i or v intrinsic material
- Two regions:
 - 1) Thin p region (High field/Avalanche region) – avalanche multiplication occurs
 - 2) Intrinsic region (Drift region) – generated holes must drift towards the p⁺ contact

Impact Ionization

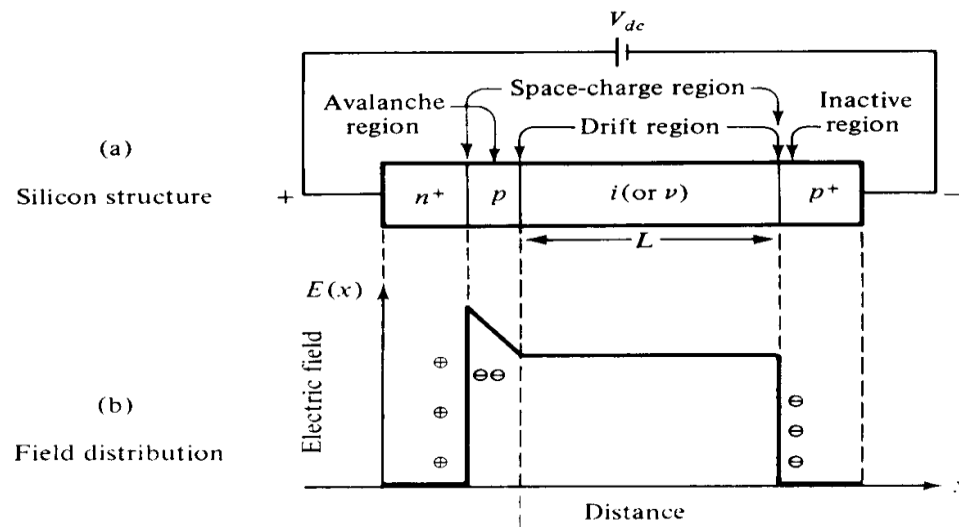
- If a free electron with sufficient energy strikes a silicon atom, it can break the covalent bond of silicon and liberate an electron from the covalent bond.
- If the electron liberated gains energy by being in an electric field and liberates other electrons from other covalent bonds then this process can cascade very quickly into a chain reaction producing a large number of electrons and a large current flow.
- This phenomenon is called **impact avalanche**.

Impact Ionization

- The space between $n^+ - p$ junction and the $i - p^+$ junction is called the space charge region
- The diode is reverse biased and mounted in a microwave cavity. The impedance of the cavity is mainly inductive which is matched with the capacitive impedance of the diode to form a resonant circuit.
- Such device can produce a negative ac resistance that in turns delivers power from the dc bias to the oscillation

Avalanche Multiplication

- When the reverse bias voltage is above the breakdown voltage, the space charge region always extends from n^+ - p junction to the i - p^+ junction through the p and the i regions.



Avalanche Multiplication

- A positive charge moves from left to right and gives a rising field.
- The maximum field which is at the $n^+ - p$ junction is about several hundred kilovolt/cm
- Carriers (holes) in the high field region near the $n^+ - p$ junction acquire energy to knock down the valence electrons in the conduction band and hence electron hole pairs are generated.
- This is **avalanche multiplication**.

Avalanche Multiplication

- The electrons move into the n^+ region and the holes drift through the space charge region to the p^+ region with a constant velocity V_d .
- The field throughout the space charge is about 5 kV/cm.

Avalanche Multiplication

The transit time of a hole across the drift i-region L is given by

$$\tau = \frac{L}{v_d}$$

And the avalanche multiplication factor is

$$M = \frac{1}{1 - (V/V_b)^n}$$

where V = applied voltage

V_b = avalanche breakdown voltage

$n = 3-6$ for silicon is a numerical factor depending on the doping of p^+ - n or n^+ - p junction

- The breakdown voltage for a silicon p⁺ -n junction can be expressed as

$$|V_b| = \frac{\rho_n \mu_n \epsilon_s |E_{\max}|^2}{2}$$

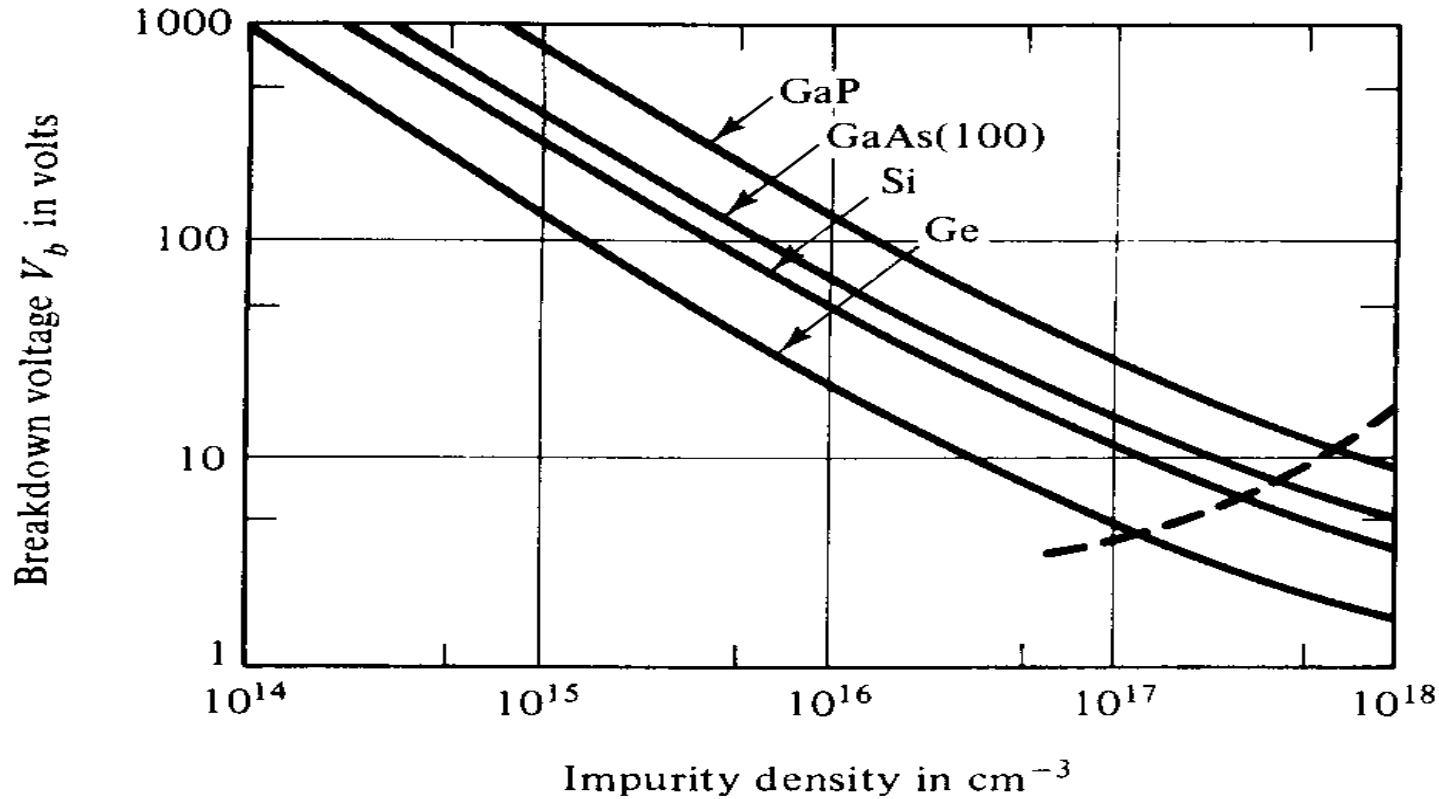
where ρ_n = resistivity

μ_n = electron mobility

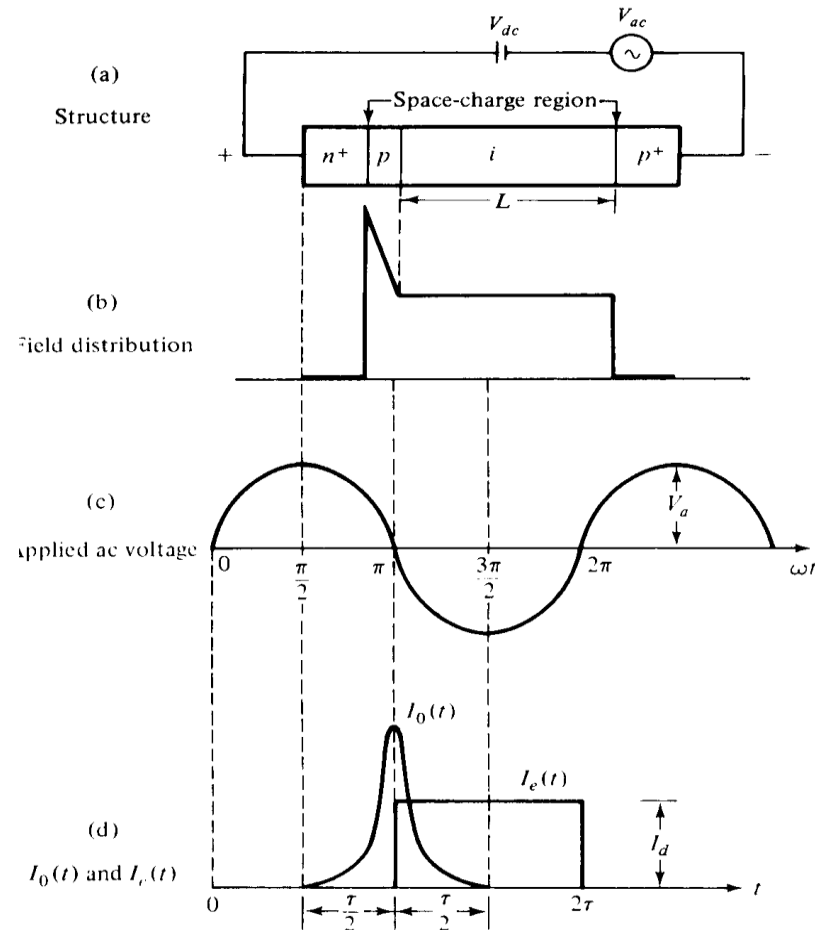
ϵ_s = semiconductor permittivity

E_{\max} = maximum breakdown of the electric field

Breakdown voltage Vs impurity doping



Carrier Current $I_0(t)$ and External Current $I_e(t)$



Carrier Current $I_o(t)$ and External Current $I_e(t)$

- The diode can be mounted in a microwave resonant circuit
- An ac voltage can be maintained at a given frequency in the circuit, and the total field across the diode is the sum of ac and dc fields which causes breakdown at the $n^+ - p$ junction during the positive half cycle of the ac voltage cycle if the field is above the breakdown voltage.
- The carrier current (hole current in this case) $I_o(t)$ generated at the $n^+ - p$ junction by the avalanche multiplication grows exponentially with time while the field is above critical voltage.

Carrier Current $I_o(t)$ and External Current $I_e(t)$

- During the negative half cycle, when the field is below breakdown voltage, the carrier current decays exponentially.
- $I_o(t)$ is in the form a pulse of very short duration and it reaches its maximum in the middle of the ac voltage cycle or one quarter of the cycle later than the voltage.

Carrier Current $I_o(t)$ and External Current $I_e(t)$

- Under the influence of electric field the generated holes are injected into the space region towards the negative terminal.
- As the injected holes traverse the drift space,
 - a. They induce a current $I_e(t)$ in the external circuit.
 - b. Cause a reduction of the field

Carrier Current $I_o(t)$ and External Current $I_e(t)$

- Since the velocity of the holes in the space charge is constant

$$I_e(t) = \frac{Q}{\tau} = \frac{v_d Q}{L}$$

where Q = total charge of the moving holes

v_d = hole drift velocity

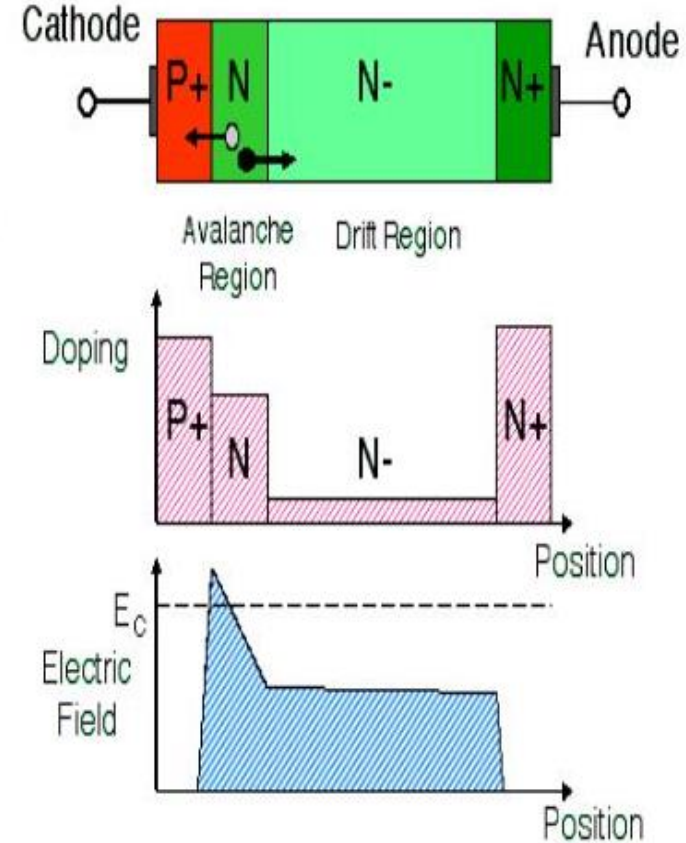
L = length of the drift i region

Carrier Current $I_o(t)$ and External Current $I_e(t)$

- The external current $I_e(t)$ because of the moving holes is delayed by 90 degree relative to the pulsed $I_o(t)$.
- Since the carrier current $I_o(t)$ is delayed by one quarter cycle or 90 degree relative to the ac voltage, $I_e(t)$ is then delayed by 180 degree relative to the voltage.
- Hence negative conductance occurs and the diode can be used for microwave oscillation and amplification.

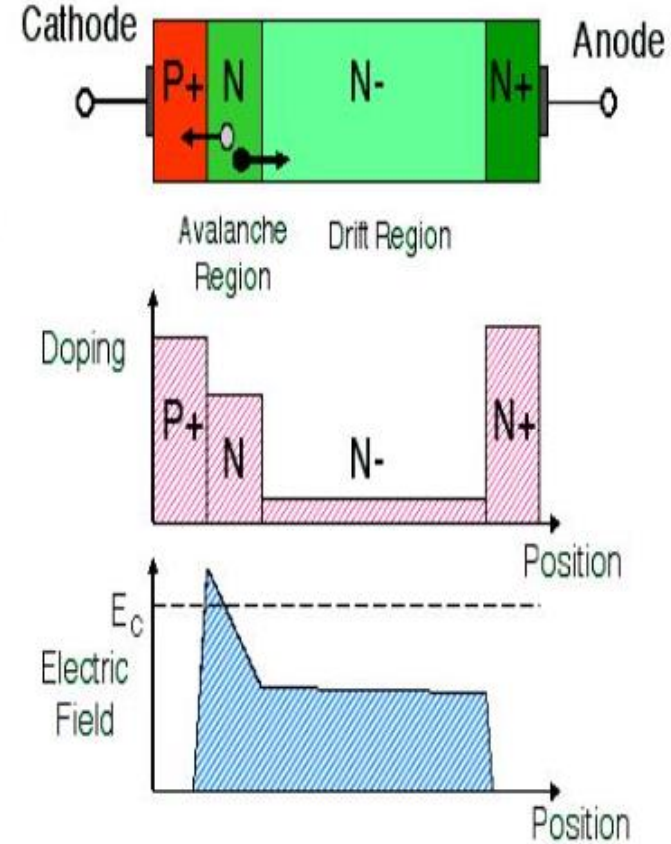
IMPATT Diode - Operation

- Diode is operated in reverse bias near breakdown, and both the N and N- regions are completely depleted
- Electric field is highly peaked in the avalanche region and nearly flat in drift region



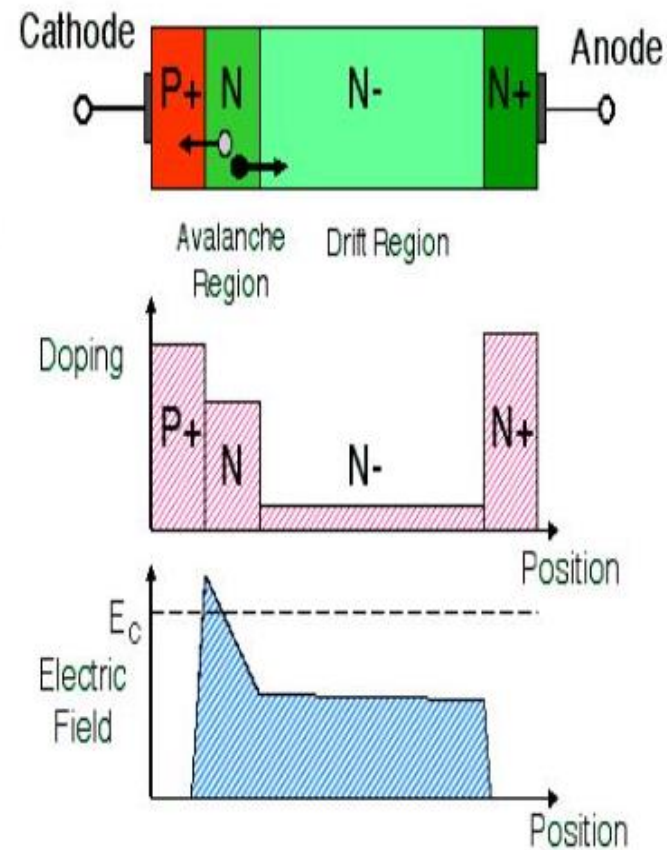
IMPATT Diode - Operation

- Avalanche breakdown occurs at the point of highest electric field, and this generates a large number of hole-electron pairs by impact ionization
- Holes swept into the cathode – electrons travel across drift region toward anode



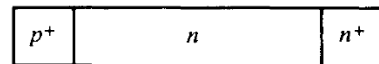
IMPATT Diode - Operation

- As they drift, they induce image charges on the anode, giving rise to a displacement current in the external circuit that is 180 degree out of phase with the nearly sinusoidal voltage waveform

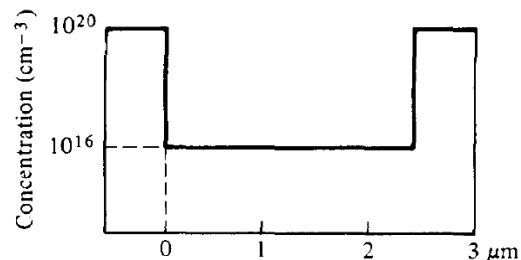


IMPATT Diode Physical Structure

(a) Abrupt p - n junction



Doping profile

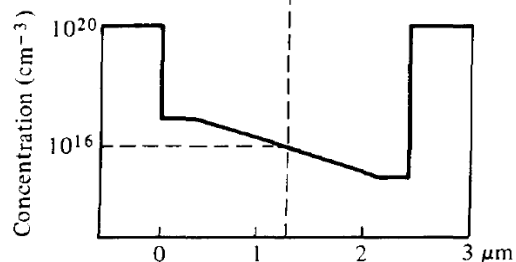


Three typical silicon IMPATT diodes

(b) Linearly graded p - n junction

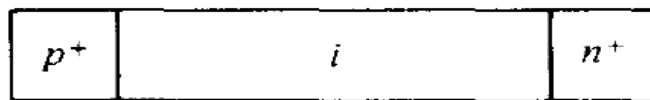


Doping profile

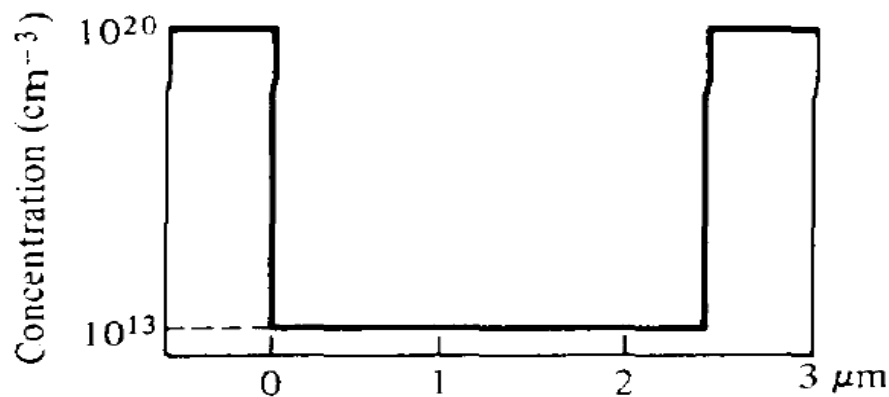


IMPATT Diode Physical Structure

(c) $p-i-n$ diode

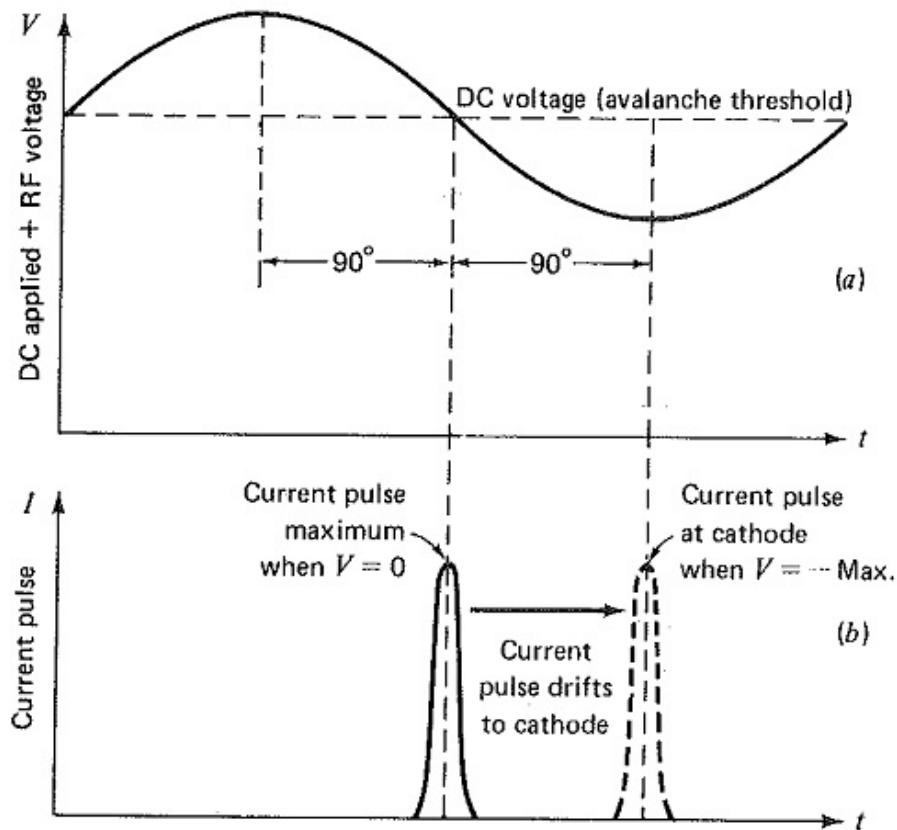


Doping profile



Three typical silicon IMPATT diodes

IMPATT Diode



(a) Applied and RF voltage

(b) Resulting current pulse and its drift across diode

IMPATT Diode – Negative Resistance

$$R = R_s + \frac{2L^2}{v_d \epsilon_s A} \frac{1}{1 - \omega^2/\omega_r^2} \frac{1 - \cos \theta}{\theta}$$

where R_s = passive resistance of the inactive region

v_d = carrier drift velocity

L = length of the drift space-charge region

A = diode cross section

ϵ_s = semiconductor dielectric permittivity

Applications of IMPATT diode

- Used in a variety of applications from low power radar systems to alarms
- In view of its high levels of phase noise, it is used in transmitters more frequently than as a local oscillator in receivers where the phase noise performance is generally more important

Applications of IMPATT diode

The following products are available as examples of IMPATT diode application:

1. Cavity stabilized IMPATT diode oscillator CIDO series
2. Pulsed IMPATT power sources IPSP series
3. IMPATT active frequency multipliers IAFM series
4. Pulsed and CW IMPATT injection-locked amplifiers IILAP and IILA series
5. Voltage controlled IMPATT oscillators VCIO series

References:

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- ❖ Annapurna Das and Sisir K Das, “Microwave Engineering”, Tata McGraw Hill Inc., 2009
- ❖ David M Pozar, “Microwave Engineering”, 3rd Edition John Wiley and Sons, Inc., 2005

THANK YOU...

